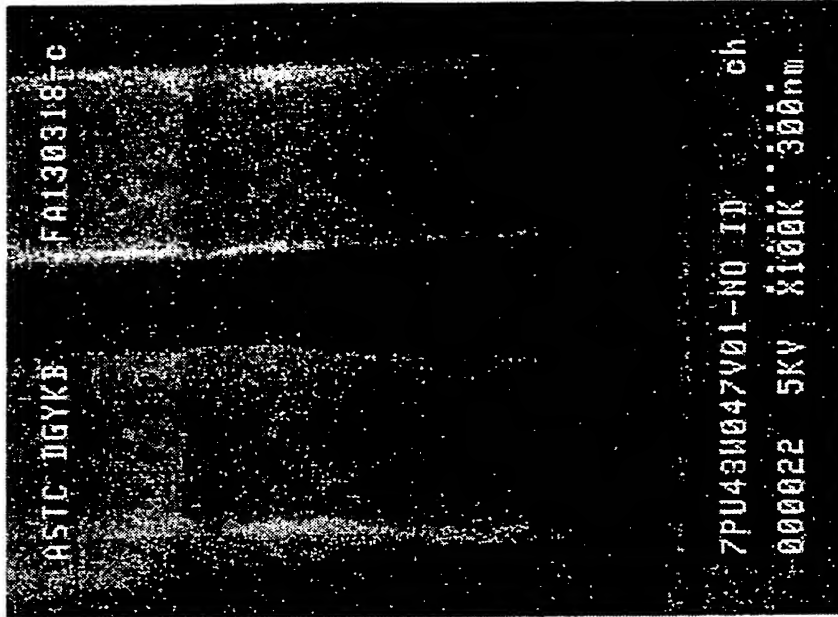


FIG. 1



SiCOH low k dielectric film formed from  
3MS and non-nitrogen containing oxidant

FIG. 2B



SiCOH low k dielectric film formed from  
3MS and N<sub>2</sub>O oxidant

FIG. 2A

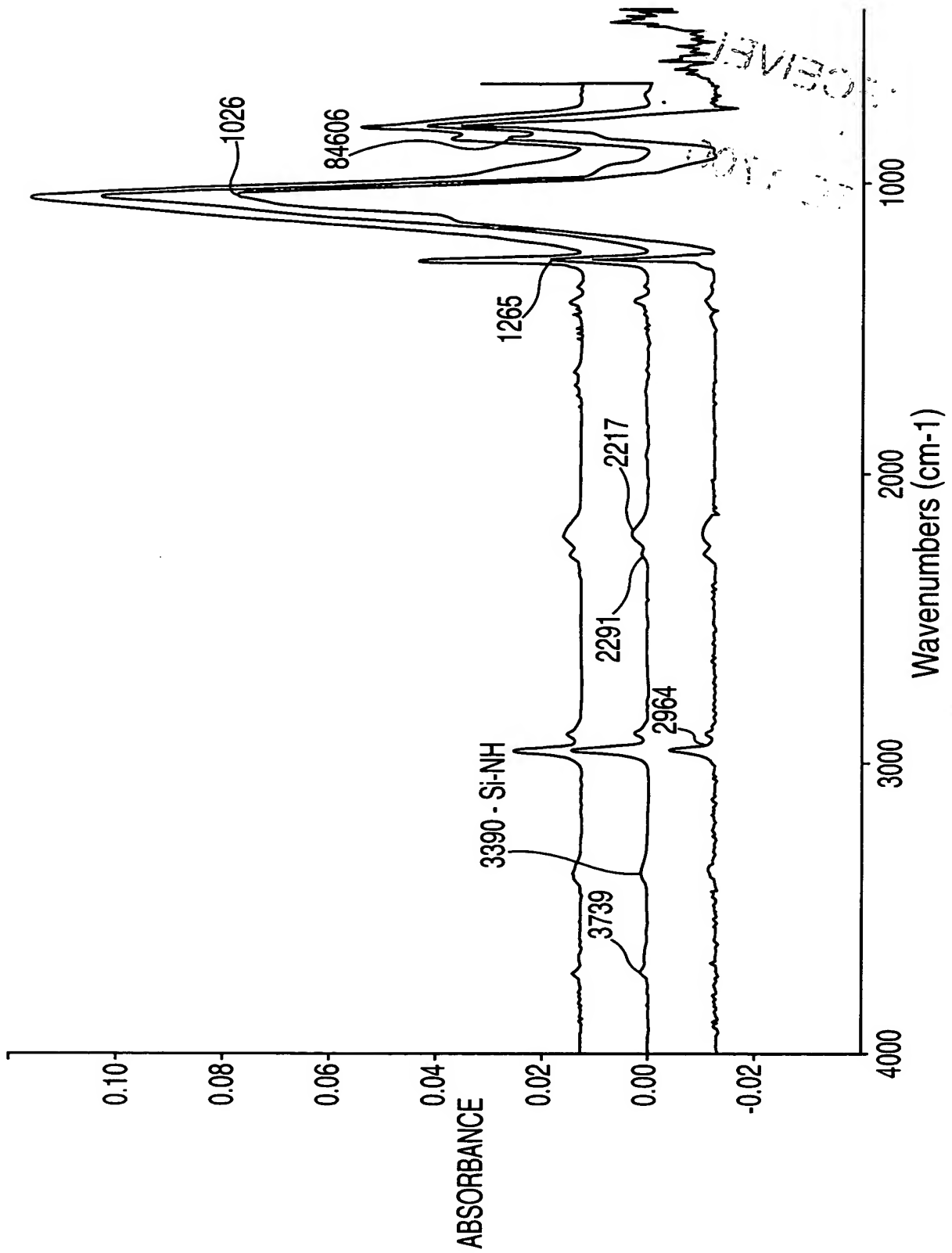


FIG. 3

